

## **APEC 2006 to Focus on the Future of Power**

### *Call for Papers Issued for Leading Power Conference; Power Industry Plans Expanded Event for New Orleans in February, 2006*

Washington, DC–June 6, 2005 -The Applied Power Electronics Conference (APEC), the leading worldwide conference and exhibit for practicing power electronics professionals, has issued a call for papers for APEC 2006. Scheduled for February 19-23, 2006, in New Orleans, the conference will feature top business and technology leaders as they focus on driving innovation and design application of power electronics. The conference is jointly sponsored by the Institute of Electrical and Electronic Engineers (IEEE) Power Electronics Society (PELS), the IEEE Industry Applications Society (IAS) and the Power Sources Manufacturers Association (PSMA).

Celebrating its 20<sup>th</sup> year with a record attendance, APEC 2005 featured 328 peer-reviewed papers presented by speakers from 28 different countries. Following the success of this year's conference, APEC 2006 has issued a call for papers in the following areas:

- AC-DC Power Supplies—single phase and multiphase ac-dc power supplies, power factor correction, multi-level active front end conversion
- DC-DC Converters—low voltage to low voltage conversion, high voltage, high power (kW to MW), microprocessor power (VRMs)
- DC-AC Inverters—dc to single phase, dc to multiphase, multilevel inverters
- Motor Drives for induction machines, permanent magnet machines, switched reluctance machines
- Power Semiconductors, Energy Storage Components and Sensors
- Energy Storage Components including magnetics, capacitors, batteries and chargers
- Mechanical Components including connectors, bus bars, substrates, thermal management
- Physical Design and Packaging topics including thermal management, integration of design tools, physical design, packaging, EMI and EMC
- Modeling, Simulation and Control of power supplies, electric machines and drives, power systems
- Business Issues such as marketing, manufacturing, quality, test, power electronics business issues, DFx, standards and regulations

Deadline for submission of paper abstracts is July 25, 2005. Authors will be notified of acceptance no later than October 10, 2005. For more information or to begin the submission process, visit:

[http://www.apec-conf.org/2006/APEC06\\_Call\\_For\\_Papers.html](http://www.apec-conf.org/2006/APEC06_Call_For_Papers.html)

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